

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Wire	Impurity	Non hazardous		0.00001	0.01	0.00001
	Pure metal	Copper (Cu)	7440-50-8	0.08936	99.99	0.10499
<b>Subtotal</b>				<b>0.08937</b>	<b>100</b>	<b>0.105</b>
Die		Silicon (Si)	7440-21-3	1.44699	100.0	1.7
	<b>Subtotal</b>				<b>1.44699</b>	<b>100</b>
Die Attach		Aromatic Polyester Resin	60088-52-0	0.00277	2.5	0.00325
		Paraffin wax	8002-74-2	0.00775	7.0	0.0091
		Epoxy resin system		0.02213	20.0	0.026
		Silver (Ag)	7440-22-4	0.07801	70.5	0.09165
<b>Subtotal</b>				<b>0.11066</b>	<b>100</b>	<b>0.13</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02598	0.05	0.03053
	Copper alloy	Zinc (Zn)	7440-66-6	0.05196	0.1	0.06105
	Copper alloy	Iron (Fe)	7439-89-6	1.19517	2.3	1.40415
	Copper alloy	Copper (Cu)	7440-50-8	50.69096	97.55	59.55427
<b>Subtotal</b>				<b>51.96407</b>	<b>100</b>	<b>61.05</b>
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	0.48517	100.0	0.57
				<b>Subtotal</b>		
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	0.68856	1.5	0.80895
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.36085	9.5	5.12335
	Filler	Silica fused	60676-86-0	40.39528	88.0	47.4584
	Carbon Black	Carbon black	1333-86-4	0.45904	1.0	0.5393
<b>Subtotal</b>				<b>45.90373</b>	<b>100</b>	<b>53.93</b>
<b>Total</b>				<b>99.99999</b>	<b>100</b>	<b>117.485</b>

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